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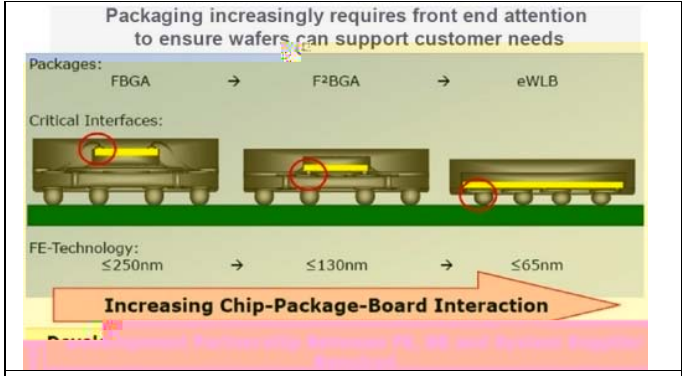
Abstract

I.



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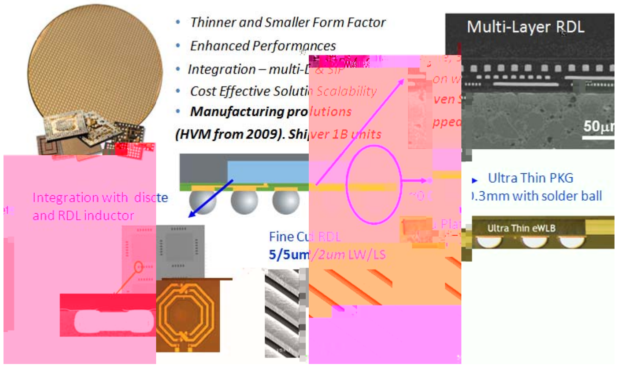
Advanced Wafer-Level Technology: eWLB/FOWLP



- *Thinner and Smaller Form Factor*
- *Enhanced Performances*
- *Integration – multi-D & SiP*
- *Cost Effective Soluti Scalability*
- ***Manufacturing pro** lutions*

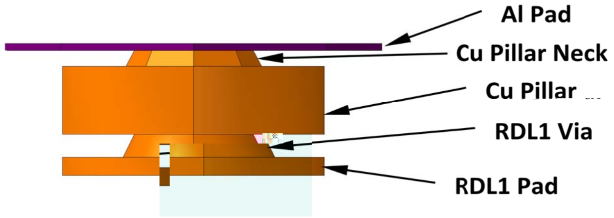
***(HVM from 2009). Shi** ver 1B units*

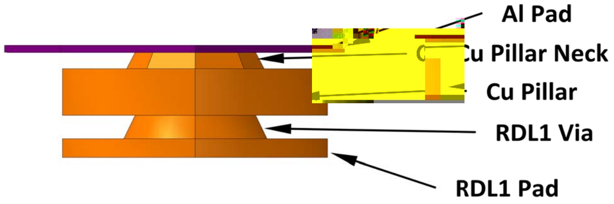
II.

Test Vehicle Specification

Reliability Test

Via Shape





Temperature (°C)	Design Option			
	1	2	3	4
250	1.00	0.91	0.87	0.79
125	1.00	0.93	1.15	1.20
25	1.00	0.88	1.04	1.09
-55	1.00	0.92	1.03	1.08

Thermal Characterization

Electrical S

1. High-
   match
2. Trace
3. Trace
   and 5
4. eWL
   talk i
   10 dB

Net	In
	flipchi
1	1.77
2	2.03
3	1.51
4	1.08